



SOT1229

plastic extremely thin small outline package; no leads; 6 terminals; body 1.2 x 1.2 x 0.4 mm

8 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|---|
| Terminal position code | B (bottom) |
| Package type descriptive code | XSON6 |
| Package type industry code | DFN1212-6 |
| Package style descriptive code | XSON (extremely thin small outline; no leads) |
| Package style suffix code | NA (not applicable) |
| Package body material type | P (plastic) |
| Mounting method type | S (surface mount) |
| Issue date | 26-6-2013 |

Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|------|-----|------|------|------|
| D | package length | 1.15 | - | 1.2 | 1.25 | mm |
| E | package width | 1.15 | - | 1.2 | 1.25 | mm |
| A | seated height | 0.35 | - | 0.37 | 0.4 | mm |
| e | nominal pitch | - | - | 0.4 | - | mm |
| n ₂ | actual quantity of termination | - | - | 6 | - | |



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2. Package outline

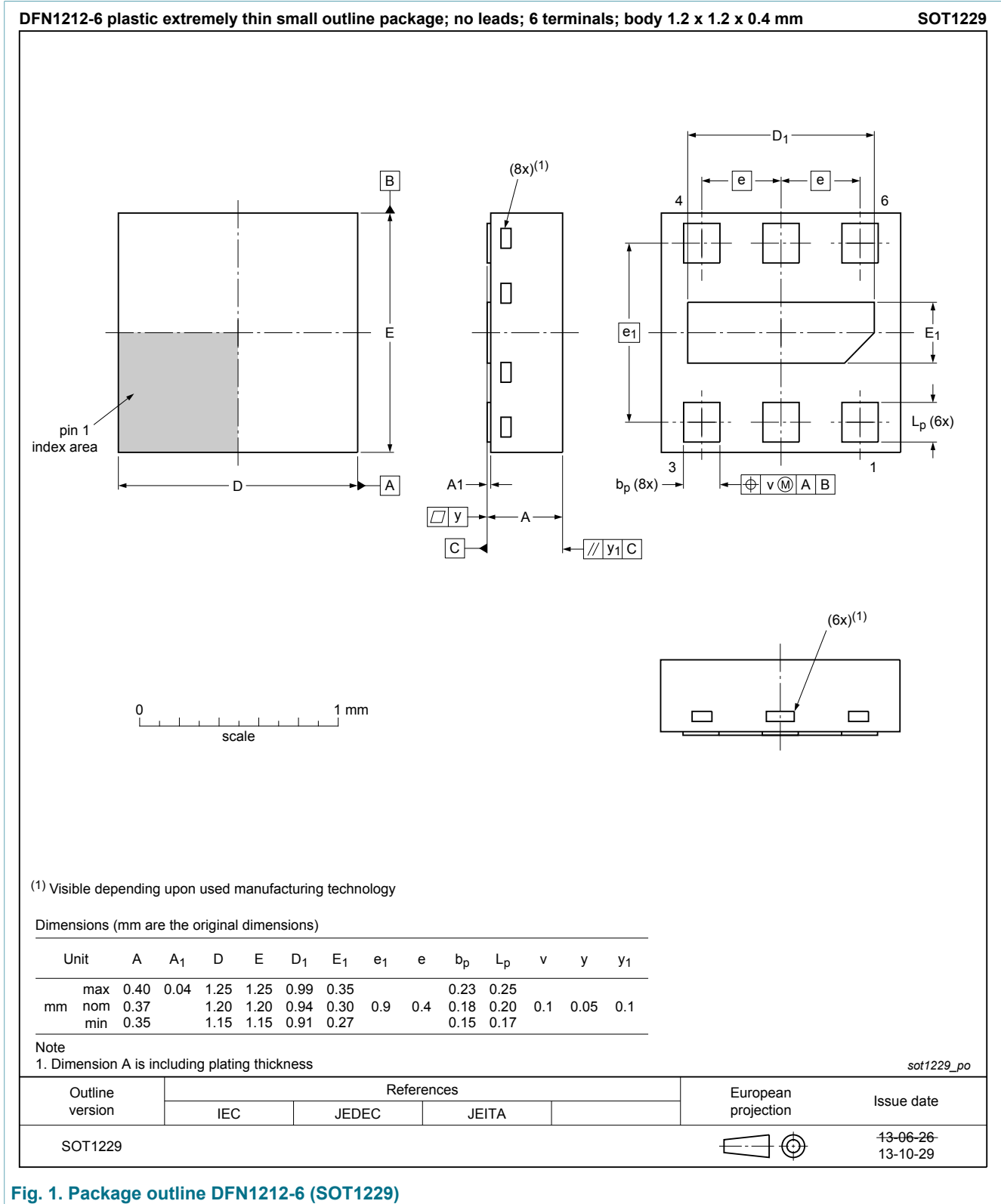


Fig. 1. Package outline DFN1212-6 (SOT1229)

3. Soldering

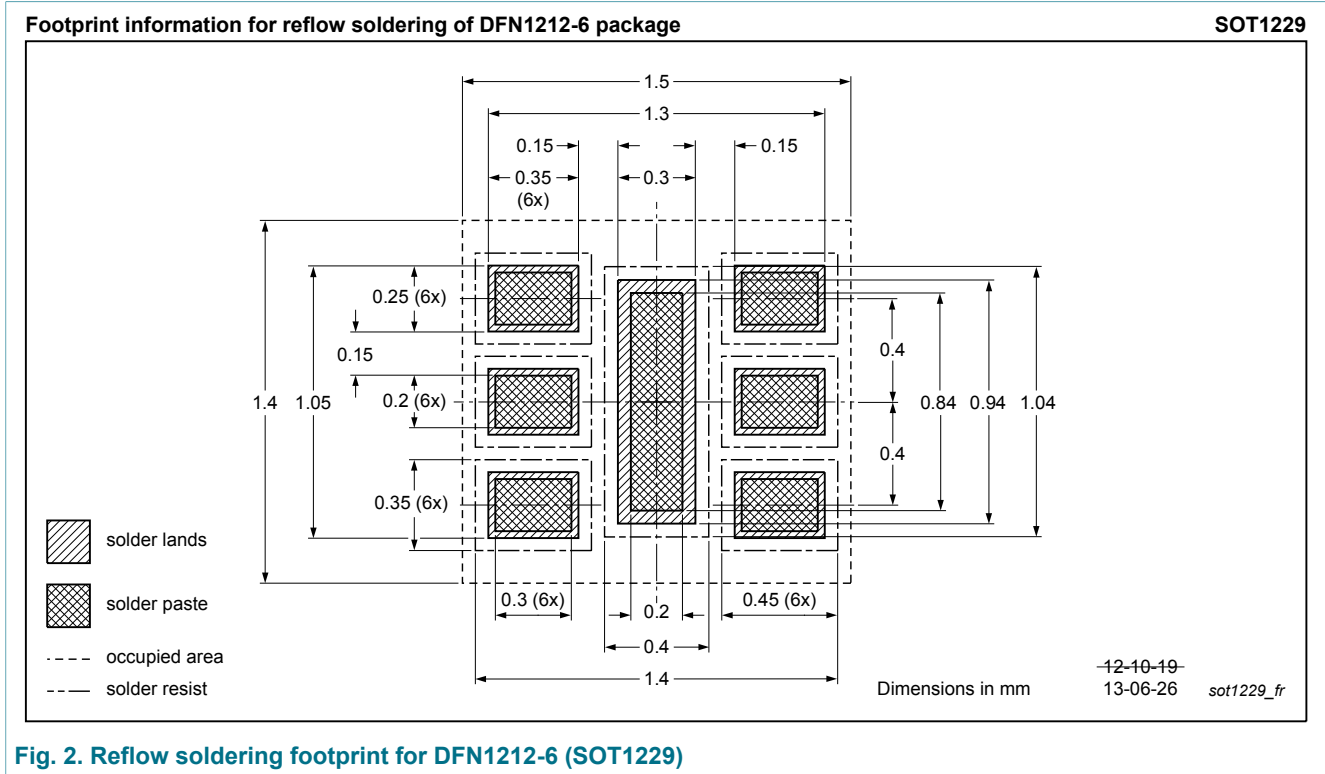


Fig. 2. Reflow soldering footprint for DFN1212-6 (SOT1229)

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4. Legal information

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